

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

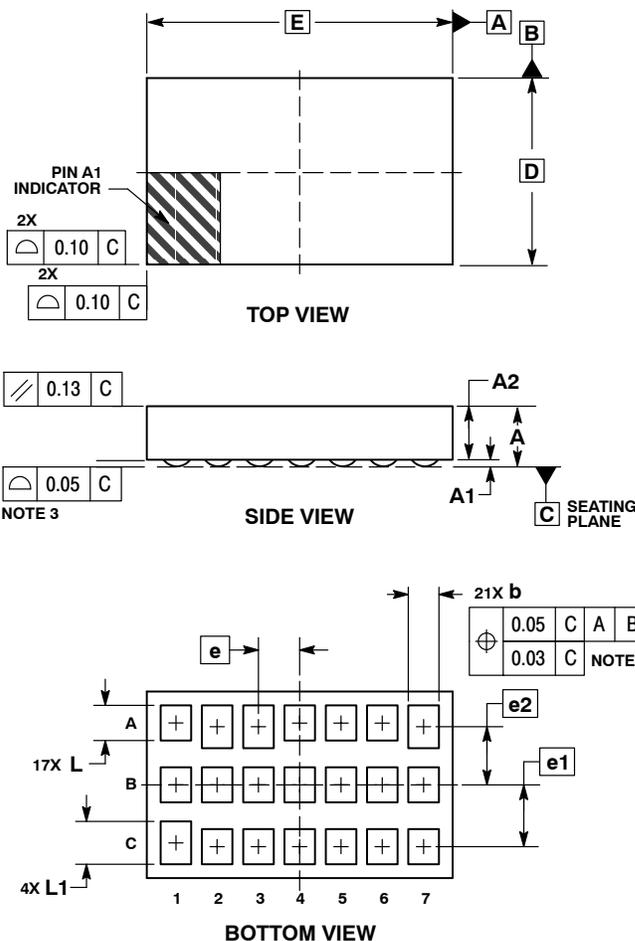
ON Semiconductor®



SCALE 2:1

SIP21, 3.10x5.08
CASE 127DF
ISSUE O

DATE 20 MAR 2014



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 4. DIMENSIONS b, L, AND L1 ARE MEASURED AT THE SURFACE OF THE PACKAGE BODY.

DIM	MILLIMETERS	
	MIN	MAX
A	---	1.14
A1	0.07	0.17
A2	0.889 REF	
b	0.470	0.546
D	3.100 BSC	
E	5.080 BSC	
e	0.686 BSC	
e1	1.029 BSC	
e2	0.965 BSC	
L	0.546	0.622
L1	0.673	0.749

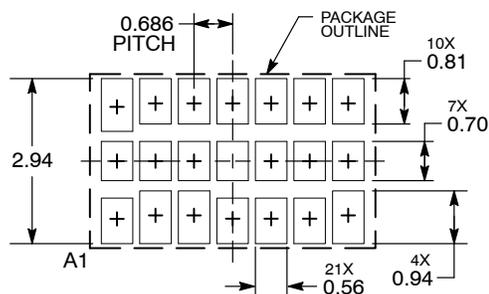
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
= Work Order Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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